



## Physical Microelectromechanical Systems (MEMS): Design, Modeling, Fabrication, and Characterization

Guest Editor:

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submissions:

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### Message from the Guest Editor

Dear Colleagues,

We will soon be celebrating 60 years of microelectromechanical systems (MEMS) since Nathanson's demonstration of the resonant gate transistor. Looking back, the field of MEMS has grown immensely, seeing commercialization in the 1980s, and widespread adoption and proliferation of sensors in the age of the Internet of Things in the past decade. The field has also seen rapid divergence, with penetration into a wide range of fields. This Special Issue seeks to focus on physical MEMS, inviting reviews and original results on MEMS sensors and MEMS actuators. We also welcome articles reporting novel applications of MEMS given trends that require going beyond devices to system integration. Of interest are reviews and new results on MEMS packaging techniques and challenges. We also invite articles on materials developments for MEMS as well as studies on MEMS reliability.





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## Editor-in-Chief

## Message from the Editor-in-Chief

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